

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **10-190321**

(43)Date of publication of application : **21.07.1998**

(51)Int.CI.

H01P 5/18

H01L 27/01

(21)Application number : 08-341534

(71)Applicant : **NEC CORP**

(22)Date of filing : **20.12.1996**

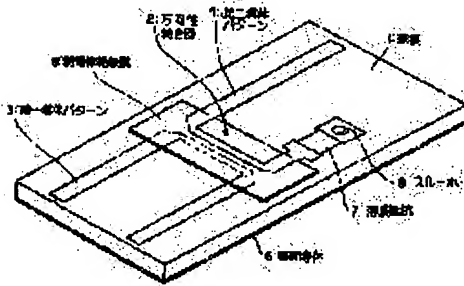
(72)Inventor : **KOIZUMI TAKAO**

(54) COUPLING ELEMENT PROVIDED WITH DIELECTRIC INSULATION FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To form the insulation film of a dielectric between the conductor patterns of a substrate surface, to improve a coupling degree between the conductor patterns by a simple structure while securing the degree of freedom on element design and to adjust the coupling degree of the conductor patterns even after the formation of an element.

SOLUTION: The dielectric insulation film 5 is formed between first and second conductor patterns 3 and 4 for constituting a directional coupler 2 on the substrate 1 and a part of the dielectric insulation film 5 is positioned at the upper part of the part for constituting the coupler of the first conductor pattern 3. Also, a part of the dielectric insulation film 5 is positioned at the lower part of the part for constituting the coupler of the second conductor pattern 4 and the two conductor patterns 3 and 4 are vertically piled up through the dielectric insulation film 5.



LEGAL STATUS

[Date of request for examination]

20.12.1996

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

2823004

[Date of registration] 04.09.1998

[Number of appeal against examiner's decision
of rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right] 04.09.2001

Copyright (C); 1998,2003 Japan Patent Office